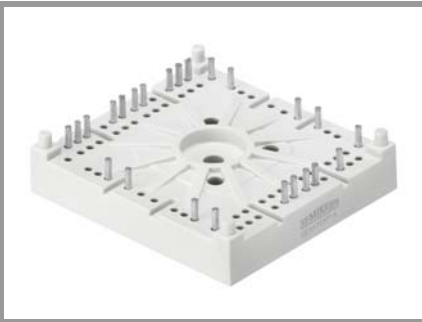


# SK 80 GD 12F4 T



**SEMITOP® 4**

## IGBT module

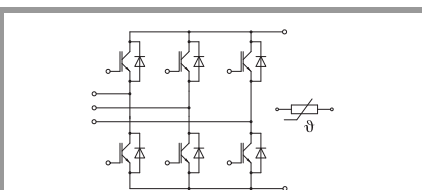
### SK 80 GD 12F4 T

#### Features\*

- One screw mounting module
- Fully compatible with SEMITOP® 1,2,3
- Improved thermal performances by aluminium oxide substrate
- Trench4 Fast IGBT technology
- CAL4F technology FWD
- Integrated NTC temperature sensor
- UL recognized, file no. E 63 532

#### Typical Applications

- Inverter



**GD-T**

| Absolute Maximum Ratings |  |                       |             |                    |
|--------------------------|--|-----------------------|-------------|--------------------|
| Symbol                   | Conditions   |                       | Values      | Unit               |
| <b>IGBT 1</b>            |  |                       |             |                    |
| $V_{CES}$                |  |                       | 1200        | V                  |
| $I_C$                    | $T_j = 150\text{ °C}$  | $T_s = 25\text{ °C}$  | 82          | A                  |
|                          |  | $T_s = 70\text{ °C}$  | 63          | A                  |
| $I_C$                    | $T_j = 175\text{ °C}$  | $T_s = 25\text{ °C}$  | 91          | A                  |
|                          |  | $T_s = 70\text{ °C}$  | 74          | A                  |
| $I_{Chom}$               |  |                       | 80          | A                  |
| $I_{CRM}$                |  |                       | 160         | A                  |
| $V_{GES}$                |  |                       | -20 ... 20  | V                  |
| $t_{psc}$                | $V_{CC} = 800\text{ V}$<br>$V_{GE} \leq 15\text{ V}$<br>$V_{CES} \leq 1200\text{ V}$ | $T_j = 150\text{ °C}$ | 10          | $\mu\text{s}$      |
| $T_j$                    |  |                       | -40 ... 175 | $^{\circ}\text{C}$ |

| Absolute Maximum Ratings |  |                      |             |                    |
|--------------------------|--|----------------------|-------------|--------------------|
| Symbol                   | Conditions                             |                      | Values      | Unit               |
| <b>Diode 1</b>           |  |                      |             |                    |
| $V_{RRM}$                | $T_j = 25\text{ °C}$                   |                      | 1200        | V                  |
| $I_F$                    | $T_j = 150\text{ °C}$                  | $T_s = 25\text{ °C}$ | 90          | A                  |
|                          |  | $T_s = 70\text{ °C}$ | 67          | A                  |
| $I_F$                    | $T_j = 175\text{ °C}$                  | $T_s = 25\text{ °C}$ | 101         | A                  |
|                          |  | $T_s = 70\text{ °C}$ | 80          | A                  |
| $I_{FRM}$                |  |                      | 200         | A                  |
| $I_{FSM}$                | 10 ms, sin 180°, $T_j = 150\text{ °C}$ |                      | 550         | A                  |
| $T_j$                    |  |                      | -40 ... 175 | $^{\circ}\text{C}$ |

| Absolute Maximum Ratings |  |  |             |                    |
|--------------------------|--|--|-------------|--------------------|
| Symbol                   | Conditions   |  | Values      | Unit               |
| <b>Module</b>            |  |  |             |                    |
| $I_{t(RMS)}$             | $\Delta T_{terminal}$ at PCB joint = 30 K, per pin |  | 60          | A                  |
| $T_{stg}$                |  |  | -40 ... 125 | $^{\circ}\text{C}$ |
| $V_{isol}$               | AC, sinusoidal, t = 1 min                          |  | 2500        | V                  |

# SK 80 GD 12F4 T



SEMISTOP® 4

## IGBT module

### SK 80 GD 12F4 T

#### Features\*

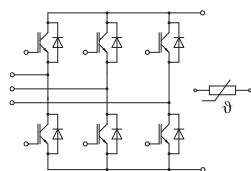
- One screw mounting module
- Fully compatible with SEMISTOP® 1,2,3
- Improved thermal performances by aluminium oxide substrate
- Trench4 Fast IGBT technology
- CAL4F technology FWD
- Integrated NTC temperature sensor
- UL recognized, file no. E 63 532

#### Typical Applications

- Inverter

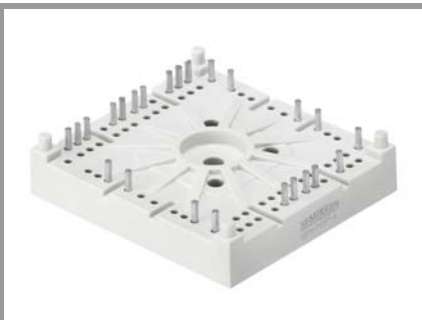
| Characteristics |  |                       | min. | typ. | max. | Unit |
|-----------------|--|-----------------------|------|------|------|------|
| Symbol          | Conditions   |                       |      |      |      |      |
| <b>IGBT 1</b>   |  |                       |      |      |      |      |
| $V_{CE(sat)}$   | $I_C = 80\text{ A}$<br>$V_{GE} = 15\text{ V}$<br>chiplevel                         | $T_j = 25\text{ °C}$  |      | 2.05 | 2.40 | V    |
|                 |  | $T_j = 150\text{ °C}$ |      | 2.59 | 2.85 | V    |
| $V_{CE0}$       | chiplevel  | $T_j = 25\text{ °C}$  |      | 0.80 | 0.90 | V    |
|                 |  | $T_j = 150\text{ °C}$ |      | 0.70 | 0.80 | V    |
| $r_{CE}$        | $V_{GE} = 15\text{ V}$<br>chiplevel  | $T_j = 25\text{ °C}$  |      | 16   | 19   | mΩ   |
|                 |  | $T_j = 150\text{ °C}$ |      | 24   | 26   | mΩ   |
| $V_{GE(th)}$    | $V_{GE} = V_{CE}, I_C = 3\text{ mA}$   |                       | 5.2  | 5.8  | 6.4  | V    |
| $I_{CES}$       | $V_{GE} = 0\text{ V}$<br>$V_{CE} = 1200\text{ V}$                                  | $T_j = 25\text{ °C}$  |      |      | 1.36 | mA   |
|                 |  |                       |      | -    |      | mA   |
| $C_{ies}$       | $V_{CE} = 25\text{ V}$<br>$V_{GE} = 0\text{ V}$                                    | $f = 1\text{ MHz}$    |      | 4.6  |      | nF   |
| $C_{oes}$       |  | $f = 1\text{ MHz}$    |      | 0.37 |      | nF   |
| $C_{res}$       |  | $f = 1\text{ MHz}$    |      | 0.27 |      | nF   |
| $Q_G$           | $V_{GE} = -15V...+15V$   |                       |      | 275  |      | nC   |
| $R_{Gint}$      | $T_j = 25\text{ °C}$   |                       |      | 2.4  |      | Ω    |
| $t_{d(on)}$     | $V_{CC} = 600\text{ V}$  | $T_j = 150\text{ °C}$ |      | 155  |      | ns   |
| $t_r$           | $I_C = 80\text{ A}$<br>$V_{GE\ neg} = -15\text{ V}$<br>$V_{GE\ pos} = 15\text{ V}$ | $T_j = 150\text{ °C}$ |      | 51   |      | ns   |
|                 |  | $T_j = 150\text{ °C}$ |      | 5.8  |      | mJ   |
| $t_{d(off)}$    | $R_{G\ on} = 3.3\text{ Ω}$   | $T_j = 150\text{ °C}$ |      | 345  |      | ns   |
| $t_f$           | $R_{G\ off} = 3.3\text{ Ω}$  | $T_j = 150\text{ °C}$ |      | 42   |      | ns   |
| $E_{off}$       | $di/dt_{on} = 2300\text{ A/μs}$<br>$di/dt_{off} = 2200\text{ A/μs}$                | $T_j = 150\text{ °C}$ |      | 5    |      | mJ   |
|                 |  |                       |      |      |      |      |
| $R_{th(j-s)}$   | per IGBT, $\lambda_{paste}=0.8\text{ W/(mK)}$                                      |                       |      | 0.51 |      | K/W  |

| Characteristics |  |                       | min. | typ. | max. | Unit |
|-----------------|--|-----------------------|------|------|------|------|
| Symbol          | Conditions   |                       |      |      |      |      |
| <b>Diode 1</b>  |  |                       |      |      |      |      |
| $V_F$           | $I_F = 100\text{ A}$<br>chiplevel                  | $T_j = 25\text{ °C}$  |      | 2.20 | 2.52 | V    |
|                 |  | $T_j = 150\text{ °C}$ |      | 2.15 | 2.47 | V    |
| $V_{F0}$        | chiplevel  | $T_j = 25\text{ °C}$  |      | 1.30 | 1.50 | V    |
|                 |  | $T_j = 150\text{ °C}$ |      | 0.90 | 1.10 | V    |
| $r_F$           | chiplevel  | $T_j = 25\text{ °C}$  |      | 9.0  | 10   | mΩ   |
|                 |  | $T_j = 150\text{ °C}$ |      | 13   | 14   | mΩ   |
| $I_{RRM}$       | $I_F = 80\text{ A}$                                | $T_j = 150\text{ °C}$ |      | 41   |      | A    |
| $Q_{rr}$        | $di/dt_{off} = 2300\text{ A/μs}$                   | $T_j = 150\text{ °C}$ |      | 11   |      | μC   |
| $E_{rr}$        | $V_{GE} = -15\text{ V}$<br>$V_{CC} = 600\text{ V}$ | $T_j = 150\text{ °C}$ |      | 6.5  |      | mJ   |
| $R_{th(j-s)}$   | per Diode, $\lambda_{paste}=0.8\text{ W/(mK)}$     |                       |      | 0.65 |      | K/W  |



GD-T

# SK 80 GD 12F4 T



SEMITOP® 4

## IGBT module

### SK 80 GD 12F4 T

#### Features\*

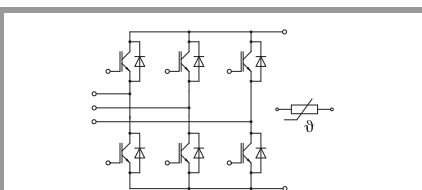
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- Improved thermal performances by aluminium oxide substrate
- Trench4 Fast IGBT technology
- CAL4F technology FWD
- Integrated NTC temperature sensor
- UL recognized, file no. E 63 532

#### Typical Applications

- Inverter

| Characteristics |             |      |      |      |      |
|-----------------|-------------|------|------|------|------|
| Symbol          | Conditions  | min. | typ. | max. | Unit |
| <b>Module</b>   |             |      |      |      |      |
| M <sub>s</sub>  | to heatsink | 2.5  |      | 2.75 | Nm   |
| w               | weight      |      | 60   |      | g    |

| Characteristics           |   |      |             |      |      |
|---------------------------|---|------|-------------|------|------|
| Symbol                    | Conditions  | min. | typ.        | max. | Unit |
| <b>Temperature Sensor</b> |   |      |             |      |      |
| R <sub>100</sub>          | T <sub>r</sub> = 100 °C   |      | 493 ± 5%    |      | Ω    |
| B <sub>100/125</sub>      | R <sub>(T)</sub> =R <sub>100</sub> exp[B <sub>100/125</sub> (1/T-1/T <sub>100</sub> )]; T[K]; |      | 3550<br>±2% |      | K    |



GD-T

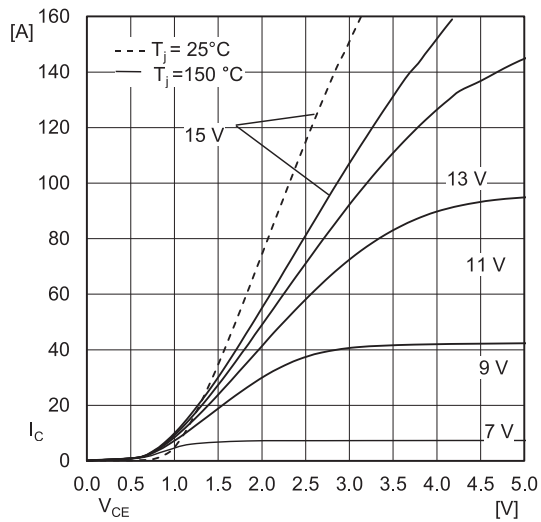


Fig. 1: Typ. IGBT1 output characteristic, incl.  $R_{CC'+EE'}$

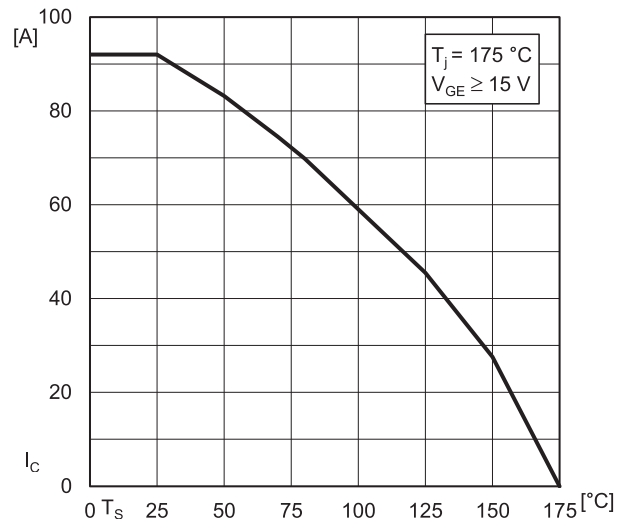


Fig. 2: Typ. rated current vs. temperature  $I_C = f(T_s)$

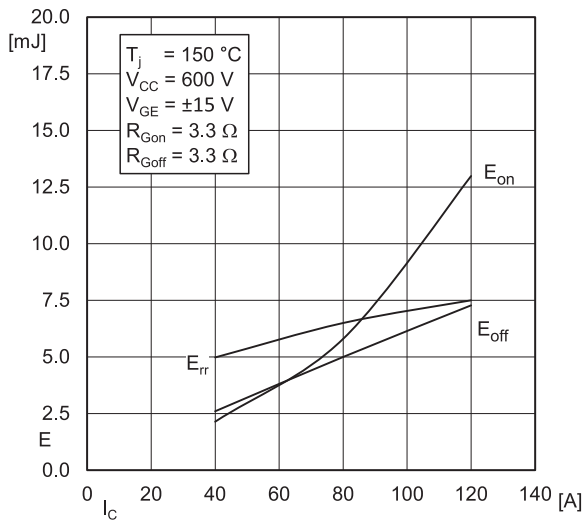


Fig. 3: Typ. turn-on /-off energy =  $f(I_C)$

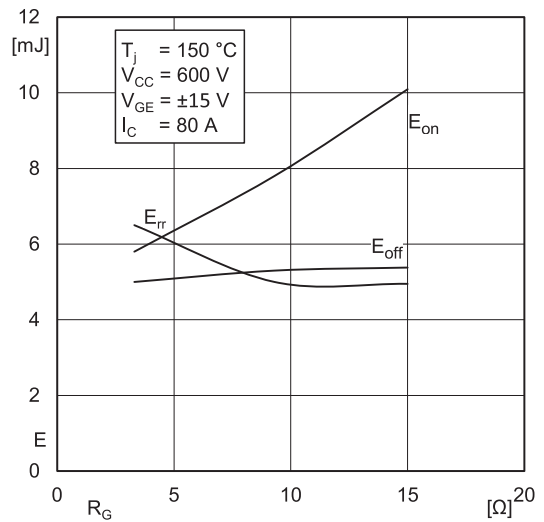


Fig. 4: Typ. turn-on /-off energy =  $f(R_G)$

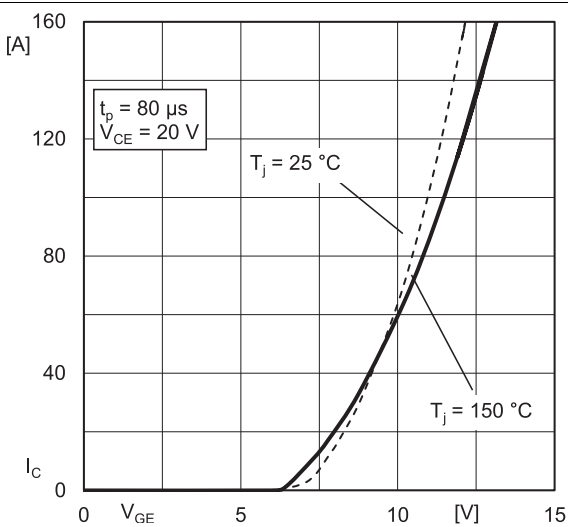


Fig. 5: Typ. transfer characteristic

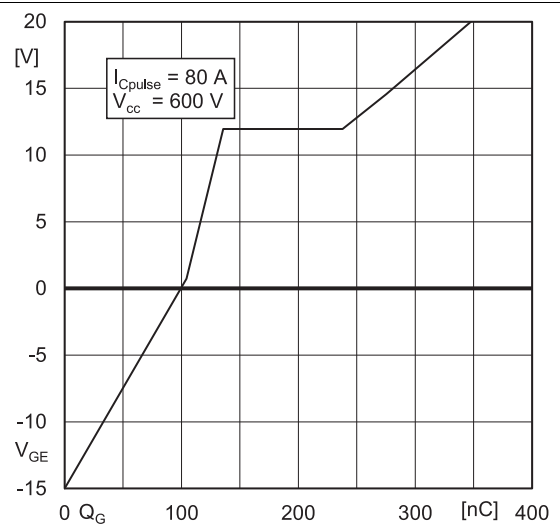
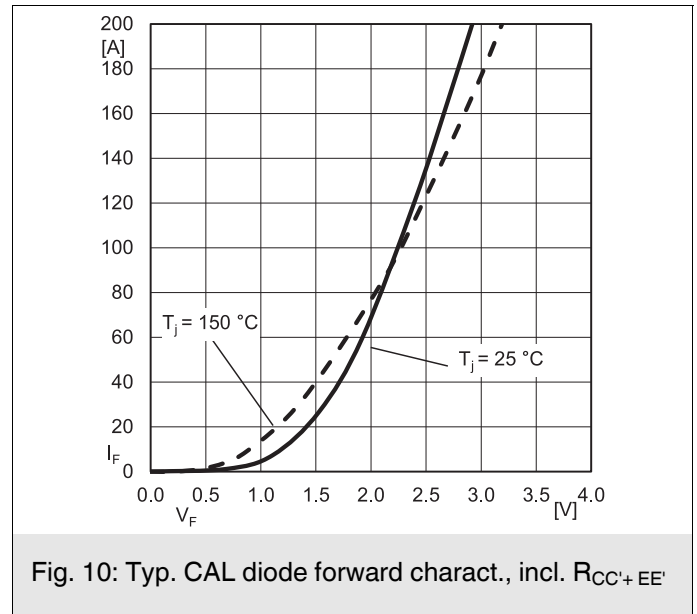
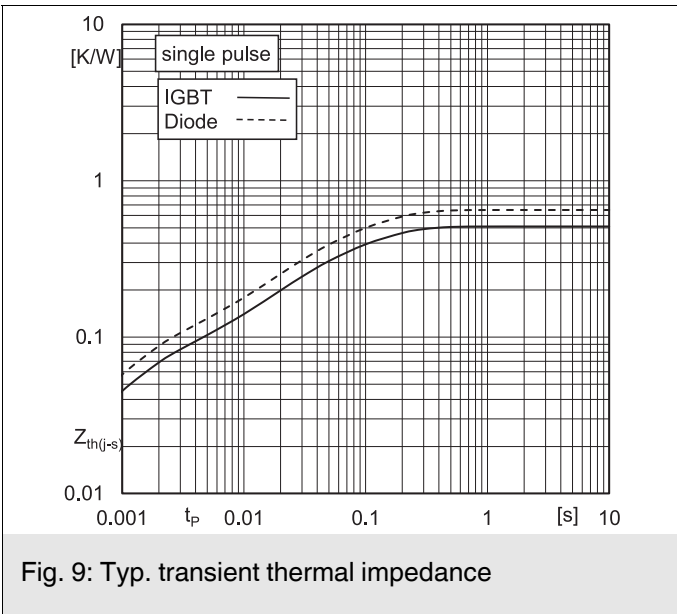
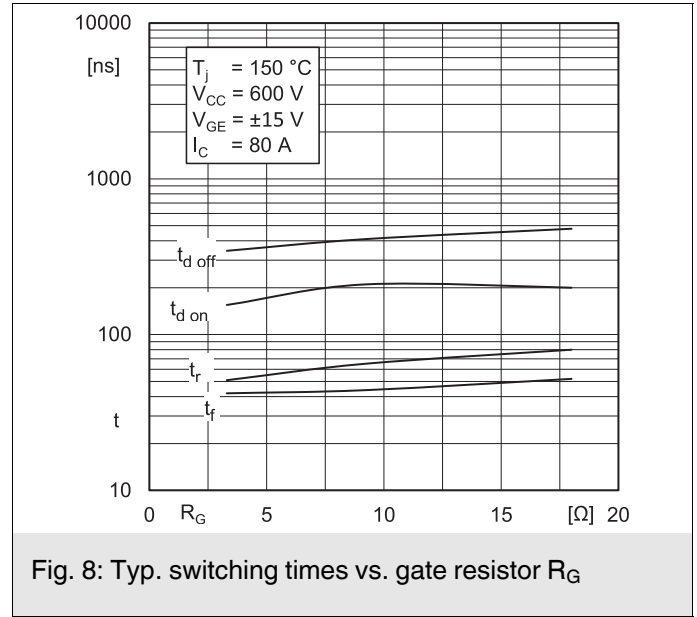
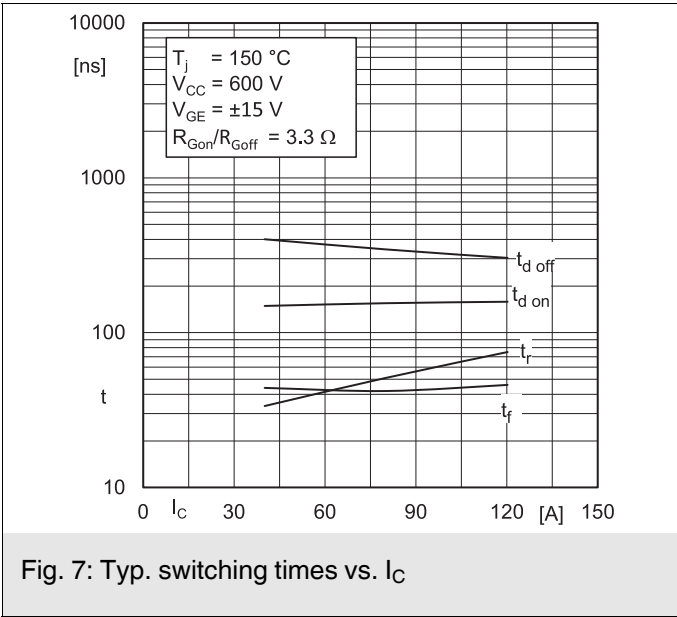


Fig. 6: Typ. gate charge characteristic





## IMPORTANT INFORMATION AND WARNINGS

This is an electrostatic discharge sensitive device (ESDS) according to international standard IEC 61340.

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